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(21) International Application Number: PCT/US96/11040 (22) International Filing Date: 27 June 1996 (27.06.96) (30) Priority Data: 08/497,019 30 June 1995 (30.06.95) US (60) Parent Application or Grant (63) Related by Continuation US 08/497,019 (CON) Filed on 30 June 1995 (30.06.95) (71) Applicant (for all designated States except US): LAMBDA TECHNOLOGIES, INC. [US/US]; Suite C, 8600 Jersey Court, Raleigh, NC 27612 (US). (72) Inventors; and (75) Inventors/Applicants (for US only): FATHI, Zakaryae [MA/US]; 101-H Stephanie Drive, Cary, NC 27511 (US). GARARD, Richard, S. [US/US]; 1908 N. Hawjek Court, Chapel Hill, NC 27516 (US). WEI, Jianghua [CN/US]; 2404 Lawrence Drive, Raleigh, NC 27603 (US). (74) Agents: SAJOVEC, F., Michael et al.; Bell, Seltzer, Park & Gibson, P.O. Drawer 34009, Charlotte, NC 28234 (US).		(81) Designated States: AL, AM, AT, AT (Utility model), AU, AZ, BB, BG, BR, BY, CA, CH, CN, CZ, CZ (Utility model), DE, DE (Utility model), DK, DK (Utility model), EE, EE (Utility model), ES, FI, FI (Utility model), GB, GE, HU, IL, IS, JP, KE, KG, KP, KR, KZ, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SK (Utility model), TJ, TM, TR, TT, UA, UG, US, UZ, VN, ARIPO patent (KE, LS, MW, SD, SZ, UG), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, ML, MR, NE, SN, TD, TG). Published <i>With international search report.</i>
(54) Title: PROCESS FOR ASSEMBLING ELECTRONICS USING MICROWAVE IRRADIATION		
(57) Abstract The present invention provides a process for assembling electronics which allows for rapid heating and fast curing, and avoids subjecting the components to potentially damaging cure conditions. The process includes applying conductive or non-conductive curable thermoplastic or thermosetting resins, having adhesive properties, to a surface of the substrate or electrical component or both. One or more electrical components may be mounted on the substrate using the adhesive properties of the resin. The resin is then subjected to variable frequency microwave irradiation selected to cure the resin without adversely affecting the substrate or electrical components. <pre> graph TD 5[5. APPLYING RESIN HAVING ADHESIVE PROPERTIES TO SUBSTRATE AND/OR ELECTRONIC COMPONENTS] --> 7[7. MOUNTING ELECTRONIC COMPONENTS ON SUBSTRATE] 7 --> 9[9. SUBJECTING RESIN TO VARIABLE FREQUENCY MICROWAVE IRRADIATION TO CURE] </pre>		